

Product / Package Information

Package	LFCSP - Sawn
Body Size (mm)	5 X 5 X 0.95
Lead Count	32
Terminal Finish	100 Sn
MS Number	MS012306D

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes
Last Updated	10-May-19

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	2.25E-02	84.50	845000	37.37	373739
Thermosets	Epoxy & Phenol Resin	Proprietary	3.99E-03	15.00	150000	6.63	66344
Other inorganic materials	Carbon black	1333-86-4	1.33E-04	0.50	5000	0.22	2211
Subtotal			2.66 E-02	100.00	1000000	44.23	442294

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	2.82 E-02	97.50	975000	46.89	468896
Copper & its alloys	Iron	7439-89-6	6.79 E-04	2.35	23500	1.13	11302
Copper & its alloys	Zinc	7440-66-6	3.47 E-05	0.12	1200	0.06	577
Copper & its alloys	Phosphorus	7723-14-0	8.67 E-06	0.03	300	0.01	144
Subtotal			2.89 E-02	100.00	1000000	48.09	480919

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	2.89 E-04	100.0	1000000	0.48	4809

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	1.69 E-03	100.0	1000000	2.81	28061

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	3.18 E-04	99.0	990000	0.53	5298
Precious metals	Palladium	7440-05-3	3.22 E-06	1.0	10000	0.01	54
Subtotal			3.22 E-04	100.0	1000000	0.54	5352

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	2.03 E-03	100.0	1000000	3.38	33823

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	2.19 E-04	77.00	770000	0.37	3651
Other organic materials	Acrylic resin	Proprietary	1.99 E-05	7.00	70000	0.03	332
Other organic materials	Acrylate	Proprietary	1.57 E-05	5.50	55000	0.03	261
Other organic materials	Polybutadiene derivative	Proprietary	1.28 E-05	4.50	45000	0.02	213
Thermoset	Epoxy resin	Proprietary	7.12 E-06	2.50	25000	0.01	119
Other organic materials	Butadiene Copolymer	Proprietary	4.27 E-06	1.50	15000	0.01	71
Others	Additive	Proprietary	4.27 E-06	1.50	15000	0.01	71
Others	Peroxide	Proprietary	1.42 E-06	0.50	5000	0.002	24
Subtotal			2.85 E-04	100.0	1000000	0.47	4741

Package Totals	Weight (g)	Percentage (%)	PPM
	6.01 E-02	100	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.